



EURO
CIRCUITS

BRIDGING THE GAP BETWEEN CAD & CAM

WWW.WOTS.NL



PCB Design Flow



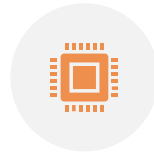
Defining your BOM
(Bill Of Material)



Create Schematics



Size the PCB and
Place Key
Components



Make the PCB Layout



Export data from
CAD for
manufacturing

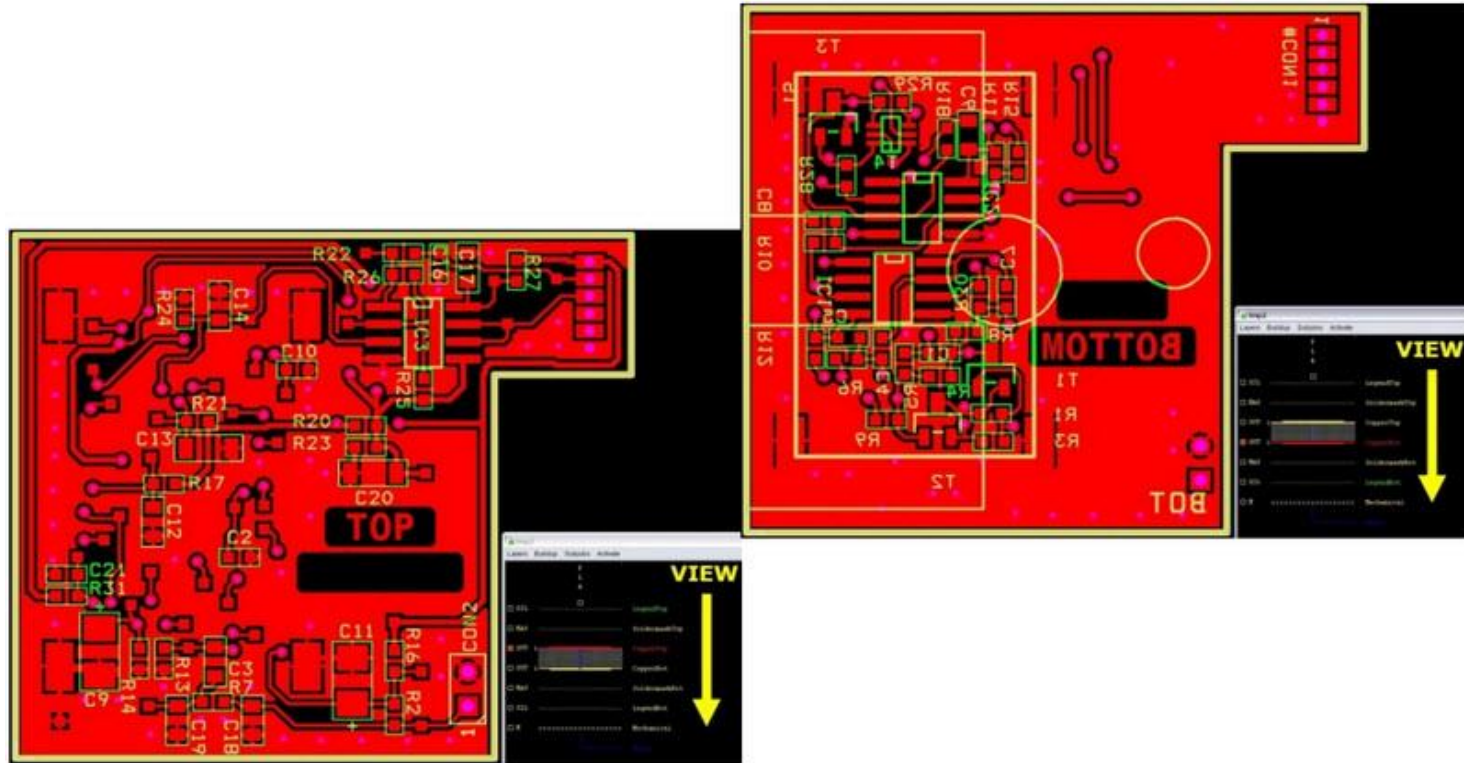
TOP DFM ISSUES

Bare Board

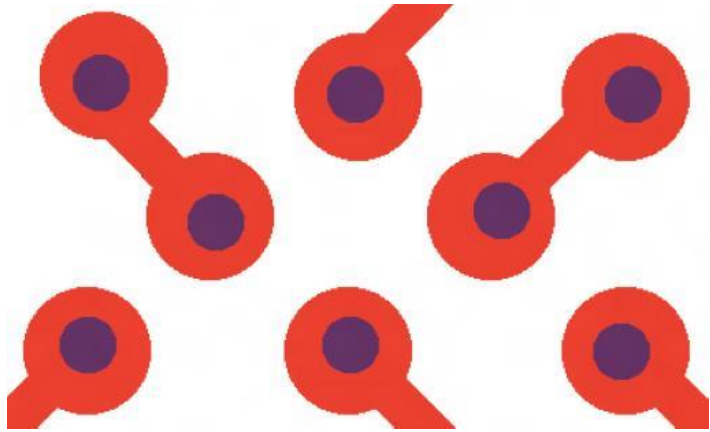
- CAD data not readable
 - CAD data not complete
 - Ambiguity between CAD data and included info files
 - Ambiguity between CAD data and online chosen order details
 - Ambiguity in the CAD data
 - More than 1 contour
 - Layer conventions
 - Mixing Imperial and Metric units
-
- Copper too close to the edge or to routing
 - Routing and contour issues
 - Open tracks
 - Annular ring problems
 - Ambiguities in the Solder Mask
 - Exposed copper
 - Covered solder pads
 - DRC violations in general
 - Plating index not OK



All layers ALWAYS viewed from the TOP



Drills versus copper pads

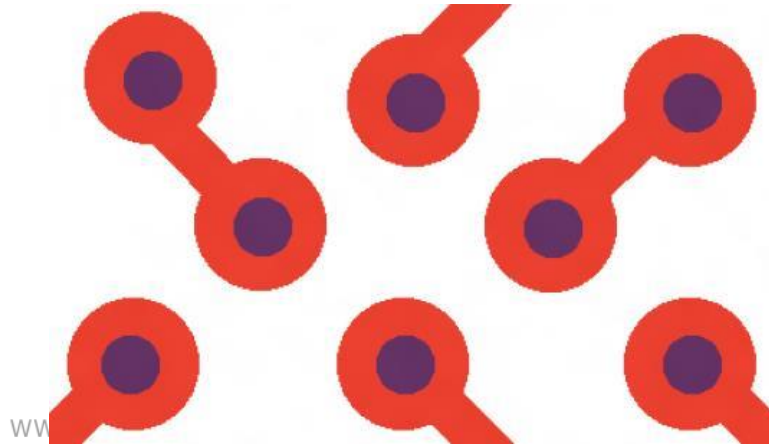


Same Unit -
Resolution

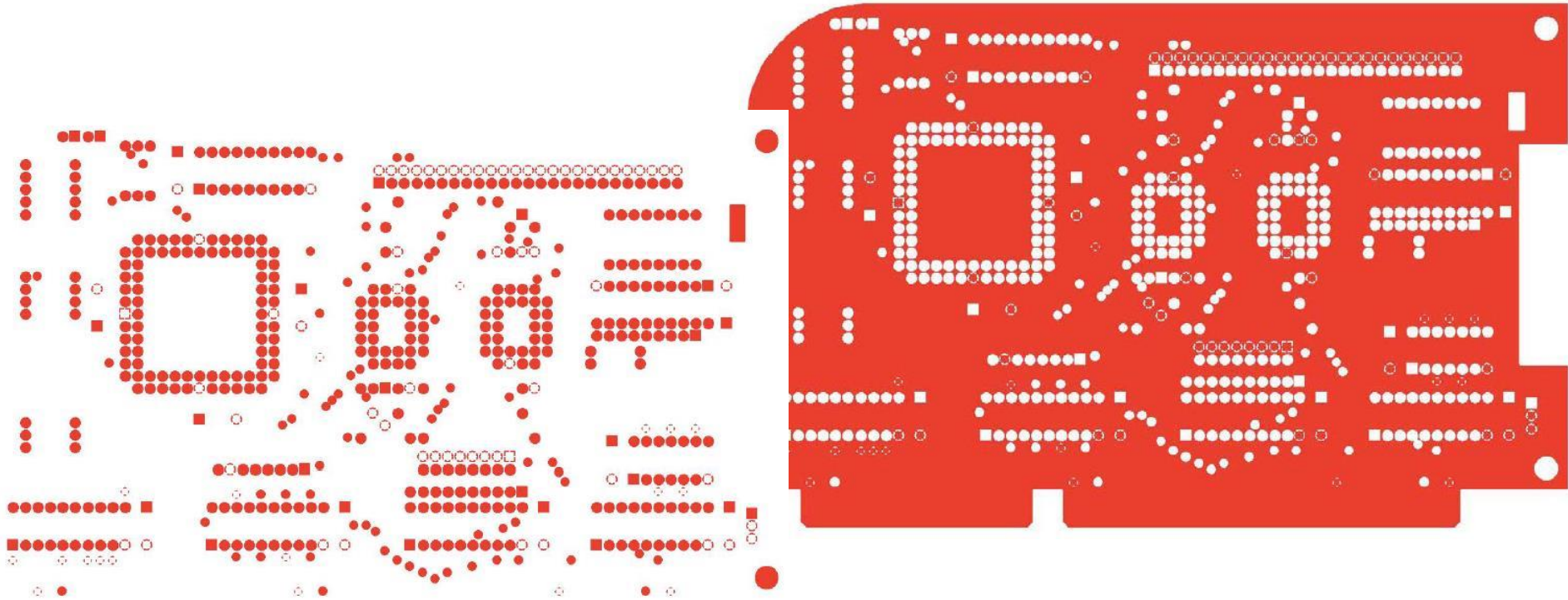
Centered

Different Unit -
Resolution

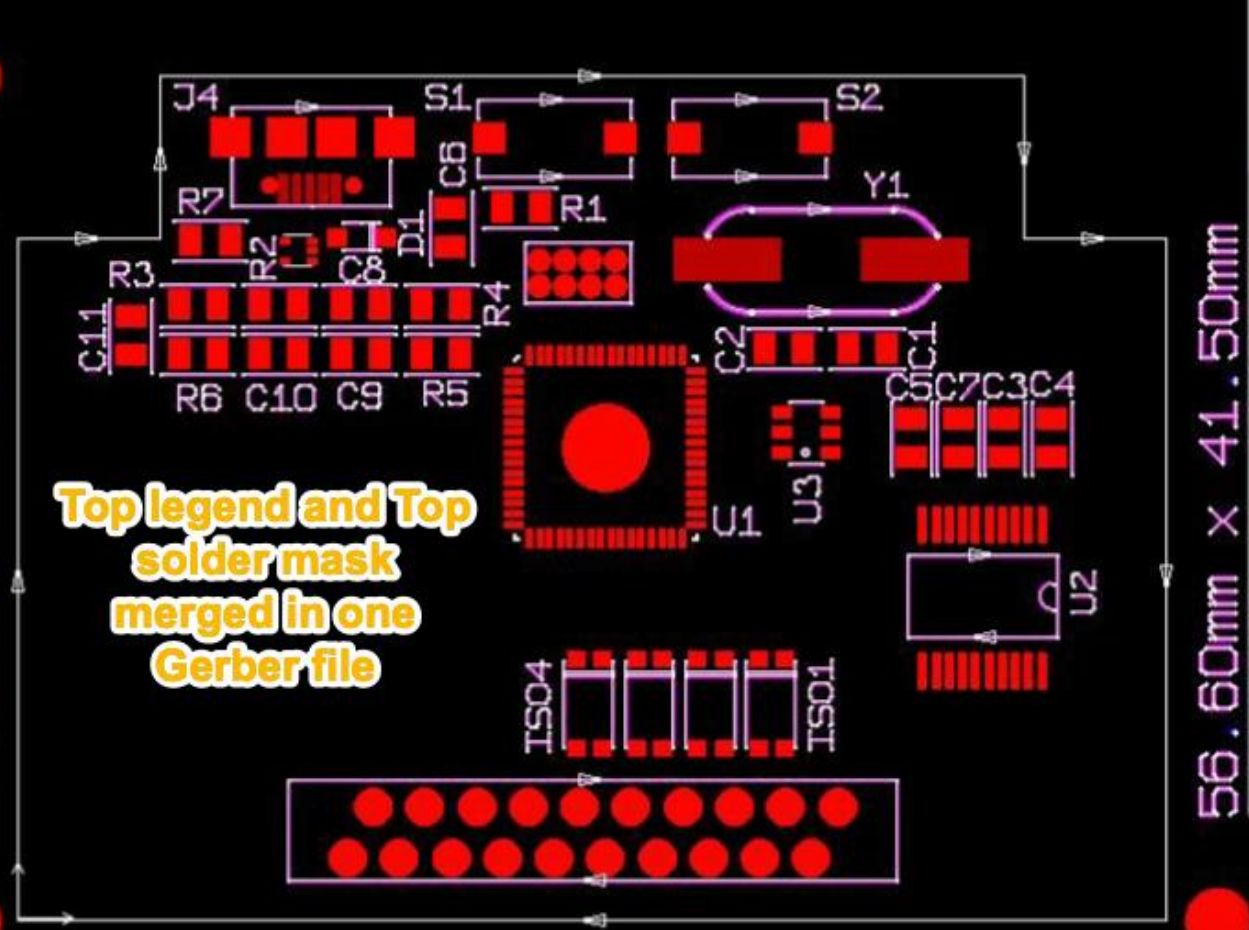
Non Centered



Layer polarity matters



TopMask BeparkAI



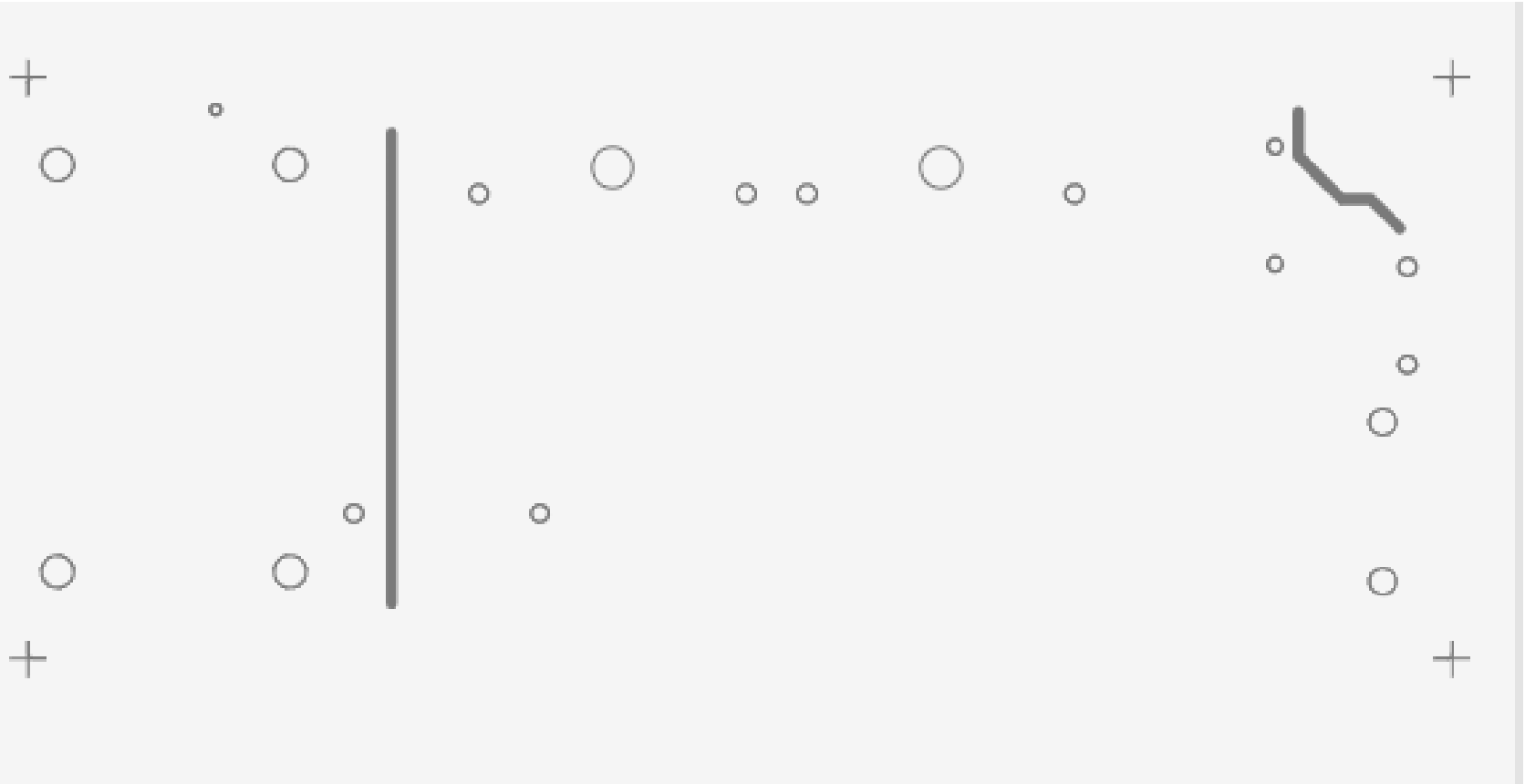
Top legend and Top solder mask merged in one Gerber file

56.60mm x 41.50mm

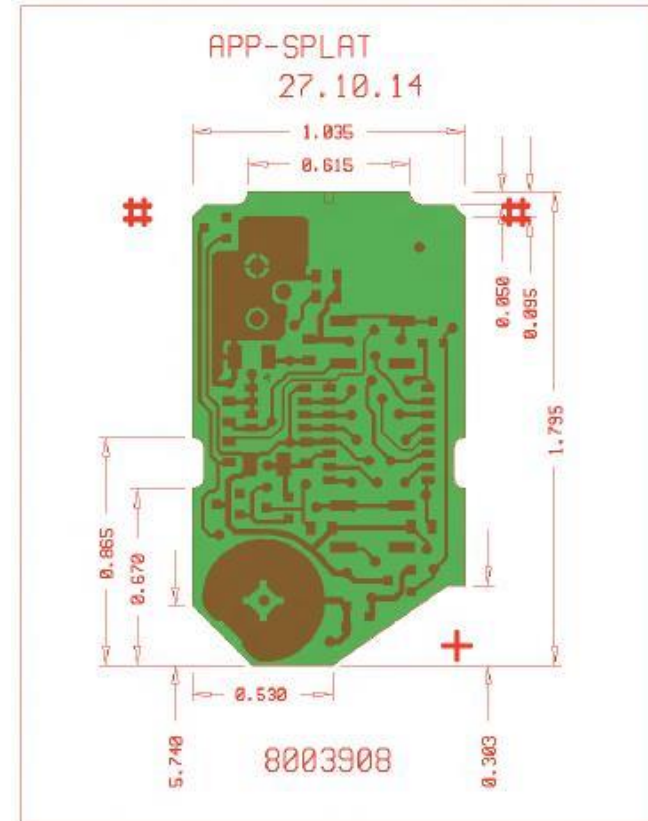
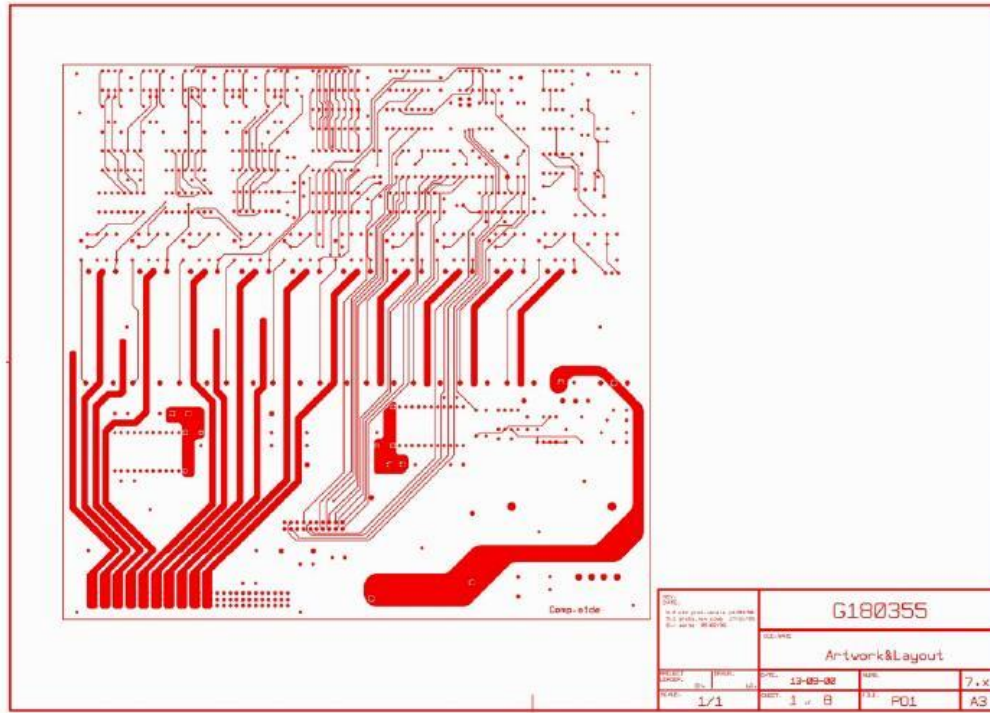
Bad output generated from CAD

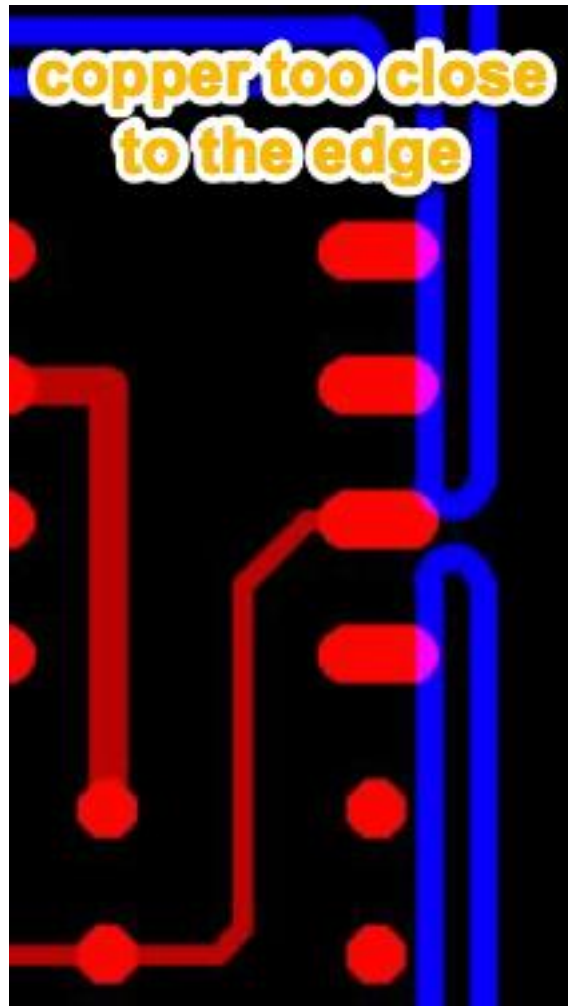


Bad outline



Data outside the PCB contour





Not respecting
the design rules

**NPTH slot cuts
through a track**



“track cut through”



annular ring issues

Board technology Select classification

Outer layer trackwidth (OL-TW)	0.150 mm	Outer layer isolation distance (OL-TT-TP-PP)	0.150 mm
Outer layer annular ring (OAR)	0.125 mm	Smallest final hole	0.25 mm
Hole density	< 1000/dm ²	Technology class	6C
Holes <= may be reduced	0.45 mm		


AR = (Pad D – Tool D) / 2 (Tool D = D drill bit)
Faulty AR = (0.650mm – 0.60mm) / 2 = **0.025mm**
Repaired AR = (0.650mm – 0.35mm) / 2 = **0.150mm**

Fault view

Outer layer annular ring (OAR) - Top copper

0 0 22

Current issue



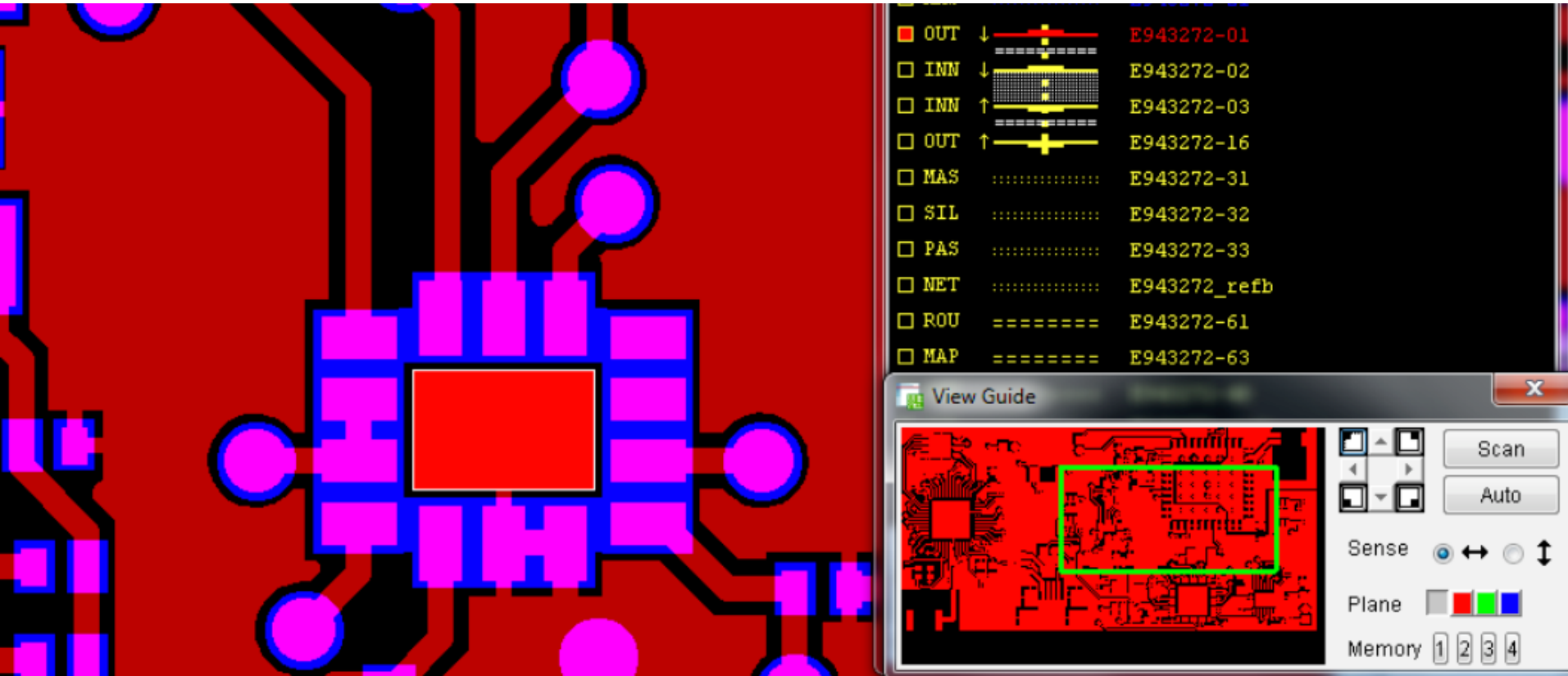
	specified	repaired
Measured annular ring:	0.025 mm	0.150 mm
Required annular ring :	0.125 mm	
Tool diameter :	0.60 mm	0.35 mm
Hole diameter :	0.50 mm	0.25 mm
Calculated pad diameter :	0.650 mm	

1 **2**

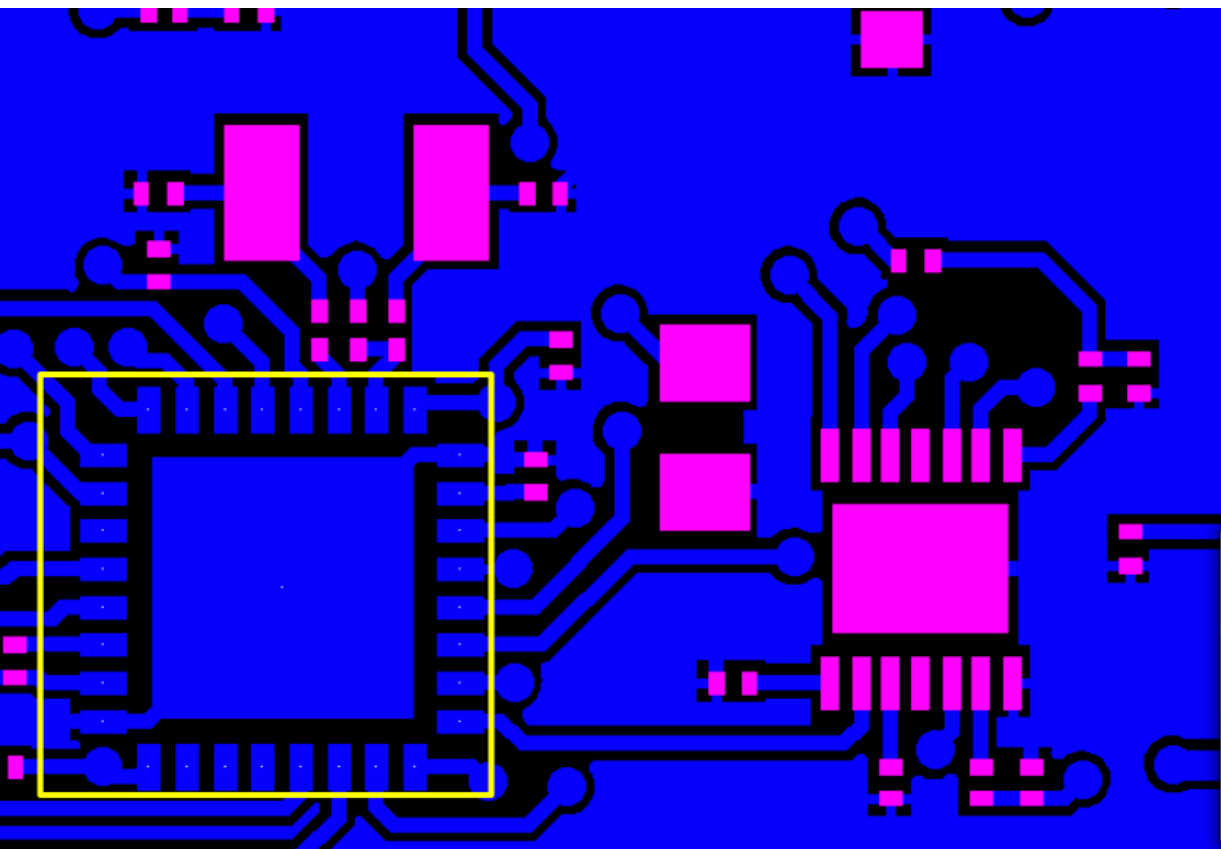
1 **2**

1/22

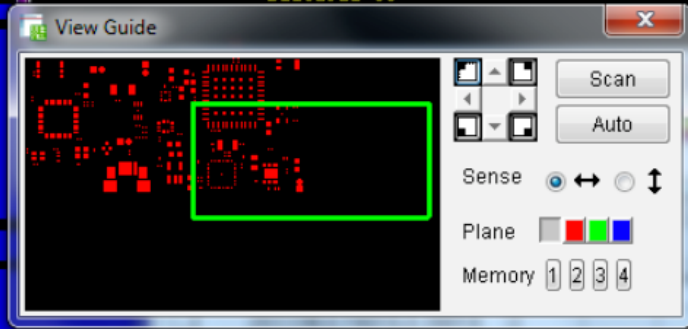
Soldermask issues



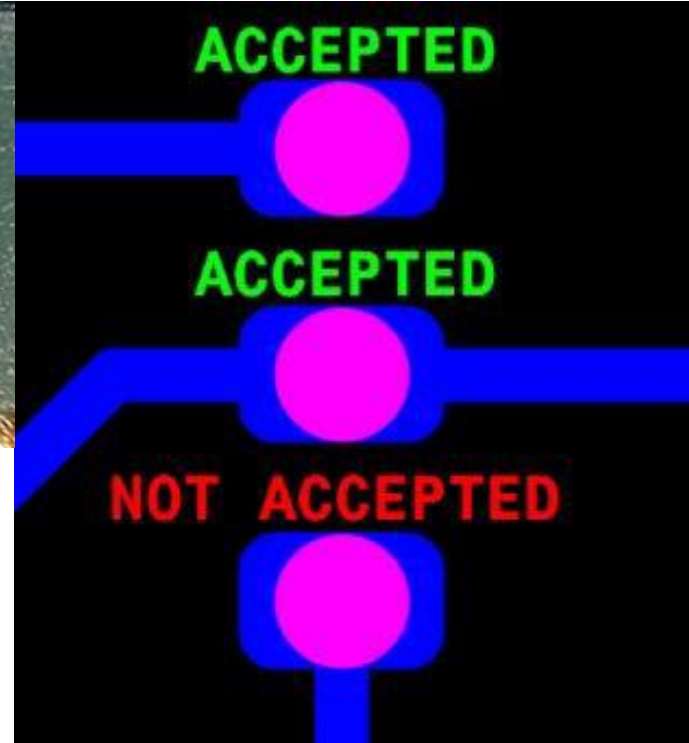
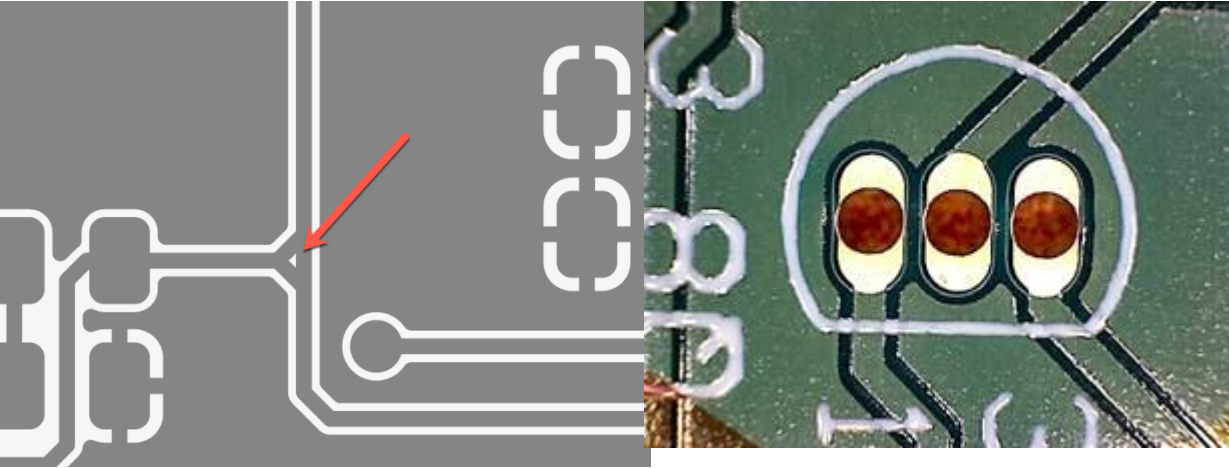
Solder paste issues



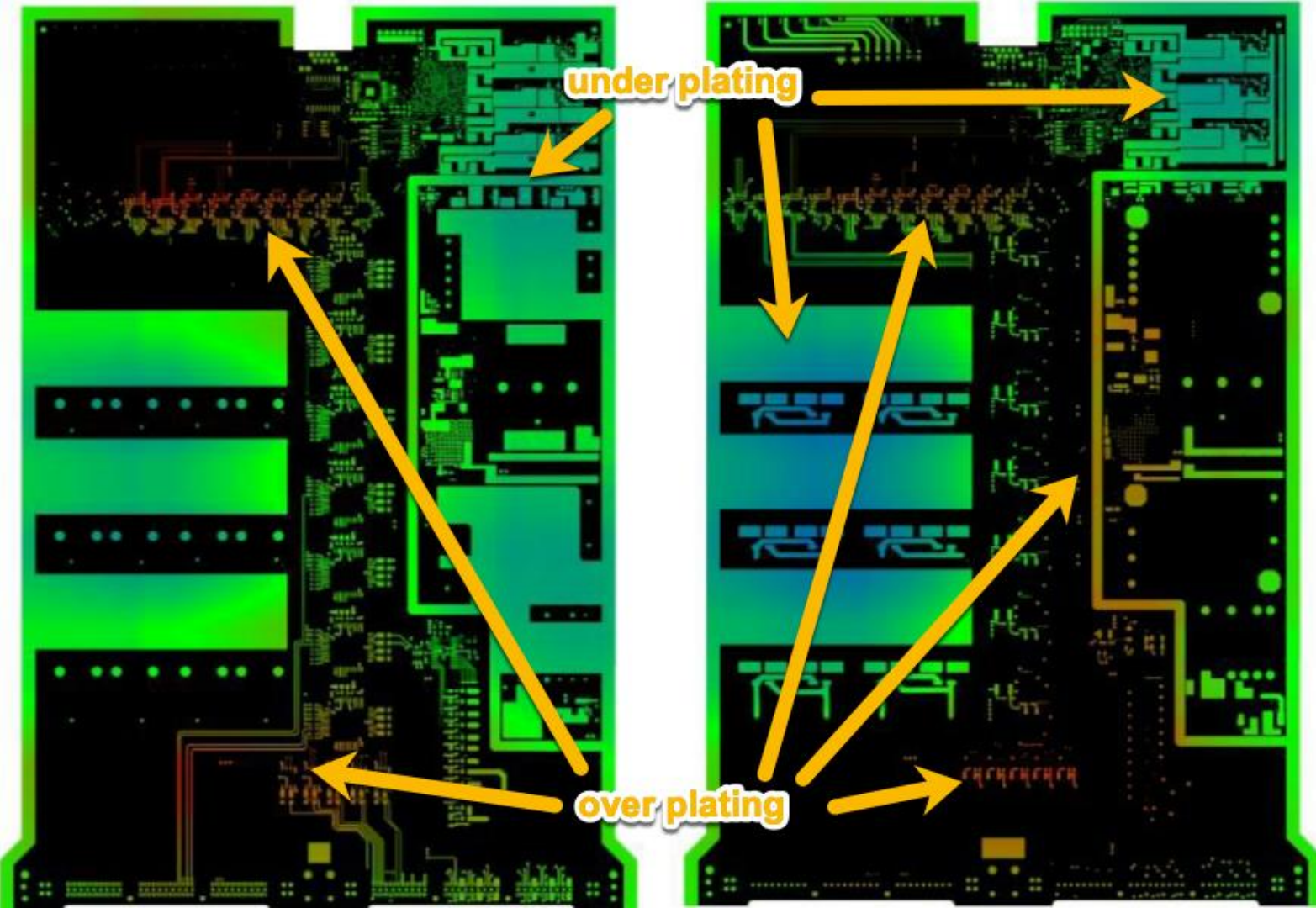
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<input type="checkbox"/>	OUT	↓	SF_v9_3_16mm_top_art
<input type="checkbox"/>	INN	↓	SF_v9_3_16mm_inner1_art
<input type="checkbox"/>	INN	↓	SF_v9_3_16mm_inner2_art
<input type="checkbox"/>	OUT	↓	SF_v9_3_16mm_bottom_art
<input type="checkbox"/>	MAS	SF_v9_3_16mm_smb_art
<input type="checkbox"/>	SIL	SF_v9_3_16mm_ssb_art
<input type="checkbox"/>	PAS	SF_v9_3_16mm_pmb_art
<input type="checkbox"/>	OUT	=====	ImageOutline
<input type="checkbox"/>	COD	=====	B1162921-code
<input type="checkbox"/>	MEC	=====	SF_v9_3_16mm_outline_art
<input type="checkbox"/>	MEC	=====	SF_v9_3_16mm_manufacturing_art
<input type="checkbox"/>	DOC	=====	SF_v9_3_16mm-1-4_dr1
<input type="checkbox"/>	DOC	=====	SF_v9_3_16mm-4-4_dr1
<input type="checkbox"/>	DOC	=====	SF_v9_3_16mm_sst_art_1
			B1162921-60



PCB production issues



NPTH : 0.15mm on toolsize (0.15mm on endsize)
PTH - Same net : 0.15mm on toolsize (0.25mm on endsize)
PTH - Diff net : 0.25mm on toolsize (0.35mm on endsize)



under plating

over plating

Plating
issues



TOP DFM ISSUES assembly

- Solder escapes
 - Cold spot - Hot spot
 - Copper unbalanced per comp (tomb stoning)
 - Pad sizes <-> geometry component
 - Footprint: component vs PCB
 - Rotation
 - Pin1 + polarity
 - Solder mask problems - Bridges not manufacturable etc...
-
- BGA - QFN - LGA ≤ 0.5 mm -> finish Che Ni/Au or Ag
 - Via in pad -> adapt layout or Via filling or No Go
 - Fiducials?
 - Panel
 - PCB
 - Component
 - Overhanging components?
 - V-Cut
 - Break bridges
 - Panel border width
 - IPC component clearance



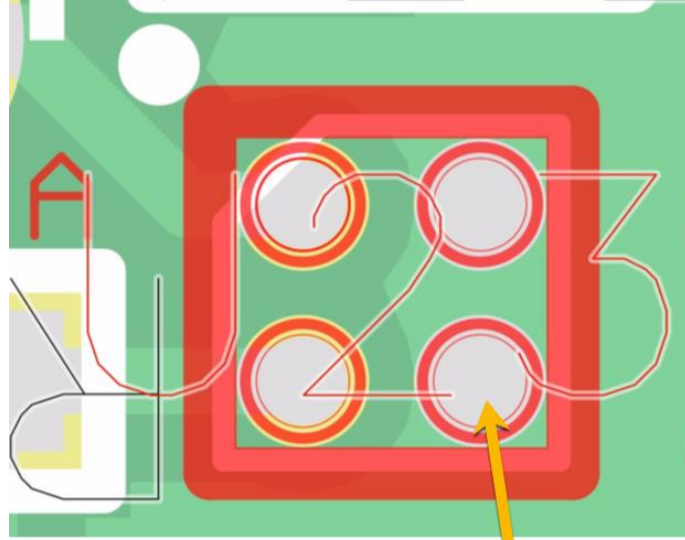
Bill Of Material - Jibberish

	A	B	C	D	E	F
10	9	10k	R_0603	0603_TYPE_B	R6, R7, R8, R9, R10, R11, R12, R25, R26	
11	6	10n	C_0603	0603_TYPE_B	C45, C46, C47, C48, C49, C50	
12	1	10u	C_0805	0805_TYPE_A	C34	
13	1	15EDGRC-3.5/6P	CON_TERMINAL_3.5MM_6-PIN	CON_TERMINAL_3.5MM_6-PIN	CN6	
14	2	18p	C_0603	0603_TYPE_B	C56, C57	
15	1	1k	R_0603	0603_TYPE_B	R13	
16	1	1u	CPOL-EUSMCA	SMC_A	C31	POLARIZED CAPACITOR, European symbol
17	2	1u	C_0603	0603_TYPE_B	C36, C39	
18	2	2.2u	CPOL-EUSMCA	SMC_A	C25, C28	POLARIZED CAPACITOR, European symbol
19	3	20k	R_0603	0603_TYPE_B	R16, R19, R22	
20	4	22	R_0603	0603_TYPE_B	R2, R3, R4, R14	
21	1	22uH	L-EUL3225M	L3225M	L1	INDUCTOR, European symbol
22	4	4.7u	CPOL-EUSMCA	SMC_A	C1, C33, C35, C37	POLARIZED CAPACITOR, European symbol
23	1	40_PIM_CON_0.5_MM_WURTH	40_PIM_CON_0.5_MMWURTH	CON_FFC_40-PIN_0.5MM_WURTH-687140149022	CN2	
24	1	5	R_0603	0603_TYPE_B	R15	
25	1	8MHz	CRYSTAL_2PIN	CRYSTAL_3.2MM_2PIN	Q1	
26	1	AP5724WG-7	AP5724	SOT23-6	IC4	
27	1	AS4C4M16S-6BIN	SDRAM_16-BIT	TFBGA-54	IC2	
28	1	IP4252C28-4-TTL,13	EMIF_4CH_IP4252	EMIF_4CH_IP4252	IC7	
29	2	IRLML2246TRPBF	BSS84	SOT23	T1, T2	P-CHANNEL MOS FET
30	1	LD-BZEN-0803	BUZZER_01	BUZZER_01	BZ1	
31	1	M95512-WMN6P	EEPROM_SPI_S08	SO08	IC5	
32	3	MAX31856MUD+	MAX31856MUD+	TSSOP14	IC8, IC9, IC10	
33	1	MCP130T-300	MCP130	SOT-23-II	IC3	
34	2	PMEG4005AEA.115	SMF5.0AT1	SOD123FL	D2, D3	200 W Transient Voltage Suppressor
35	1	SMLVT3V3	ALDO-214AA	DO-214AA	D1	
36	1	STM32F429NI	STM32F429N	TFBGA	IC1	
37	1	TSC2046	TSC2046	TSSOP16	IC11	
38	1	W25Q32FVSSIG	EEPROM_SPI_S08SOIC8_WIDE	SO08W	IC6	

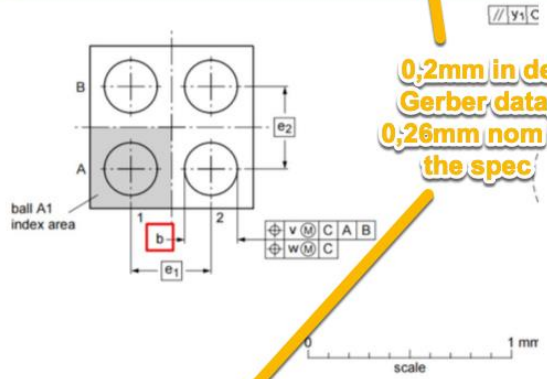
Qty	Value	Device	Package	Parts	Description
1	JP_1X14	JP_1X14	CN1		
1	JP_1X4	JP_1X4	CN5		
1	JP_1X5	JP_1X5	CN3		
1	JP_1X6	JP_1X6	CN4		
1	JUMPER_SMD_ROUND	JUMPER_SMD_ROUND		JP1	
100	R_0603	0603_TYPE_B		R17, R18, R20, R21, R23, R24	
100k	R_0603	0603_TYPE_B		R1, R27	
100n	C_0402	0402_TYPE_C		C2, C3, C4, C5, C6, C7, C8, C9, C10, C11, C12, C13, C14, C15, C16, C17	
10k	R_0603	0603_TYPE_B		R6, R7, R8, R9, R10, R11, R12, R25, R26	
10n	C_0603	0603_TYPE_B		C45, C46, C47, C48, C49, C50	
10u	C_0805	0805_TYPE_A		C34	
1	15EDGRC-3.5/6P	CON_TERMINAL_3.5MM_6-PIN		CON_TERMINAL_3.5MM_6-PIN	CN6
18p	C_0603	0603_TYPE_B		C56, C57	
1	1k	R_0603	0603_TYPE_B	R13	
1	1u	CPOL-EUSMCA	SMC_A	C31	POLARIZED CAPACITOR, European symbol
1	1u	C_0603	0603_TYPE_B	C36, C39	
2	2.2u	CPOL-EUSMCA	SMC_A	C25, C28	POLARIZED CAPACITOR, European symbol
20k	R_0603	0603_TYPE_B		R16, R19, R22	
22	R_0603	0603_TYPE_B		R2, R3, R4, R14	
1	22uH	L-EUL3225M	L3225M	L1	INDUCTOR, European symbol
1	4.7u	CPOL-EUSMCA	SMC_A	C1, C33, C35, C37	POLARIZED CAPACITOR, European symbol
1	40_PIM_CON_0.5_MMWURTH	40_PIM_CON_0.5_MMWURTH		CON_FFC_40-PIN_0.5MM_WURTH-687140149022	CN2
1	5	R_0603	0603_TYPE_B	R15	
1	8MHz	CRYSTAL_2PIN	CRYSTAL_3.2MM_2PIN	Q1	
1	AP5724WG-7	AP5724	SOT23-6	IC4	
1	AS4C4M16S-6BIN	SDRAM_16-BIT	TFBGA-54	IC2	
1	IP4252C28-4-TTL,13	EMIF_4CH_IP4252	EMIF_4CH_IP4252	IC7	
2	IRLML2246TRPBF	BSS84	SOT23	T1, T2	P-CHANNEL MOS FET
1	LD-BZEN-0803	BUZZER_01	BUZZER_01	BZ1	
1	M95512-WMN6P	EEPROM_SPI_S08	SO08	IC5	
3	MAX31856MUD+	MAX31856MUD+	TSSOP14	IC8, IC9, IC10	
1	MCP130T-300	MCP130	SOT-23-II	IC3	
2	PMEG4005AEA.115	SMF5.0AT1	SOD123FL	D2, D3	200 W Transient Voltage Suppressor
1	SMLVT3V3	DIODE_SUPPRESSOR_UNIDIRECTIONALDO-214AA	DO-214AA	D1	
1	STM32F429NI	STM32F429N	TFBGA	IC1	
1	TSC2046	TSC2046	TSSOP16	IC11	
1	W25Q32FVSSIG	EEPROM_SPI_S08SOIC8_WIDE	SO08W	IC6	

- Different file formats used
- BOM output from CAD system is limited - Cryptic description of component and package





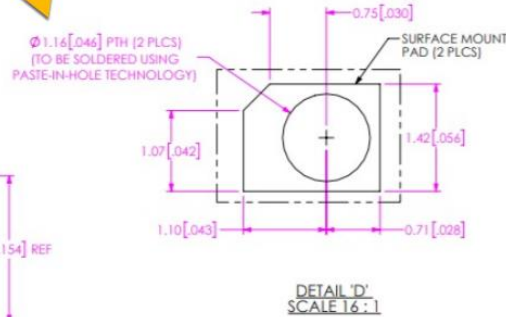
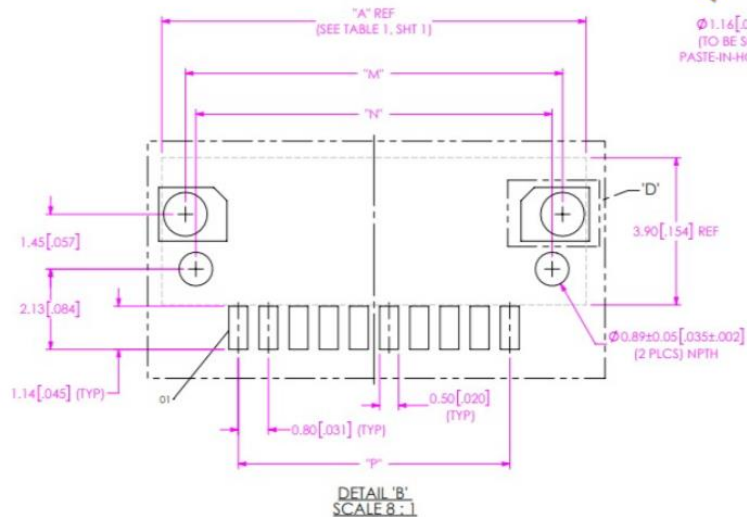
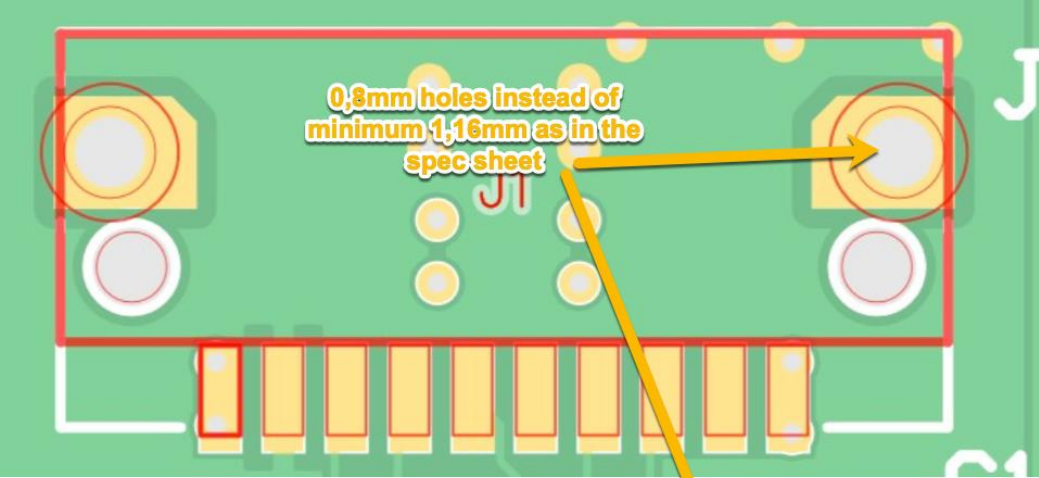
Component specs not respected in the PCB layout



0,2mm in de Gerber data,
0,26mm nom in the spec

Dimensions (mm are the original dimension)

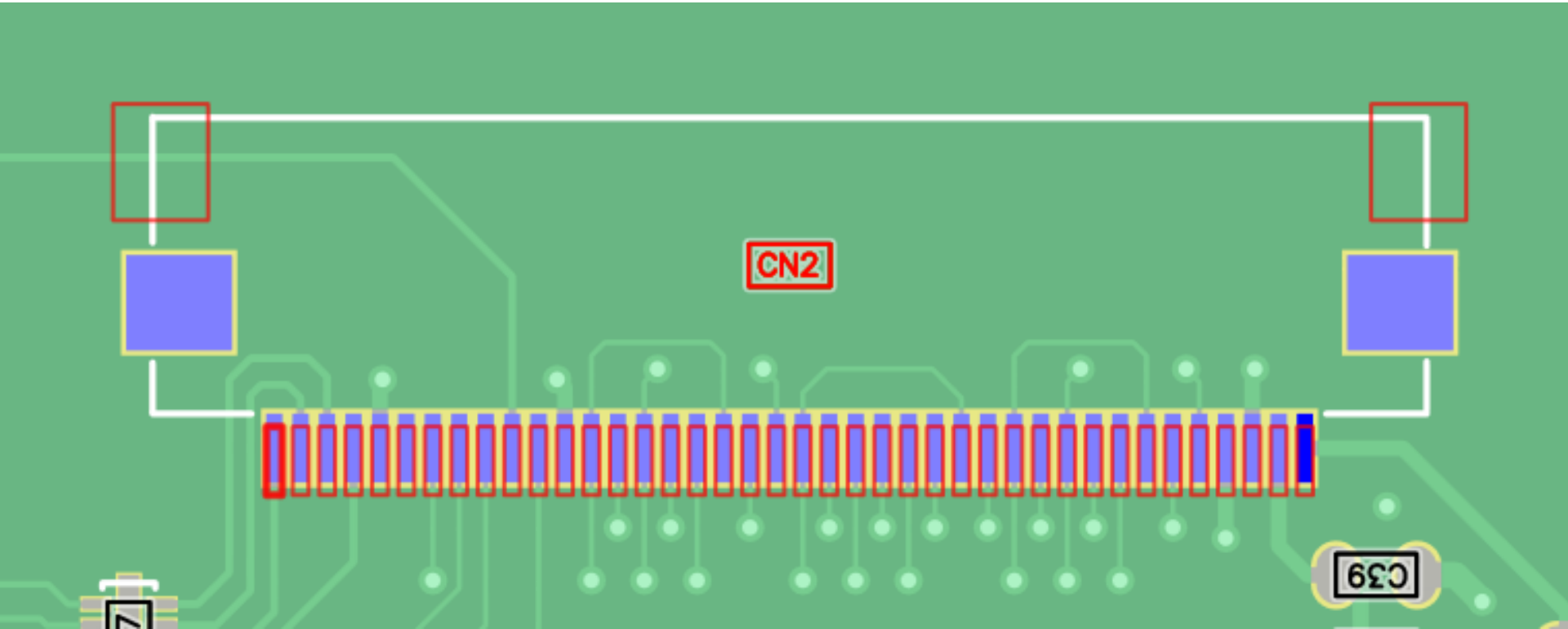
Unit	A	A ₁	A ₂	b	D	E	e ₁	e ₂	v	w	y
max	0.375	0.215	0.160	0.275	0.81	0.81					
nom	0.345	0.200	0.145	0.260	0.78	0.78	0.40	0.40	0.15	0.05	0.05
min	0.315	0.185	0.130	0.245	0.75	0.75					

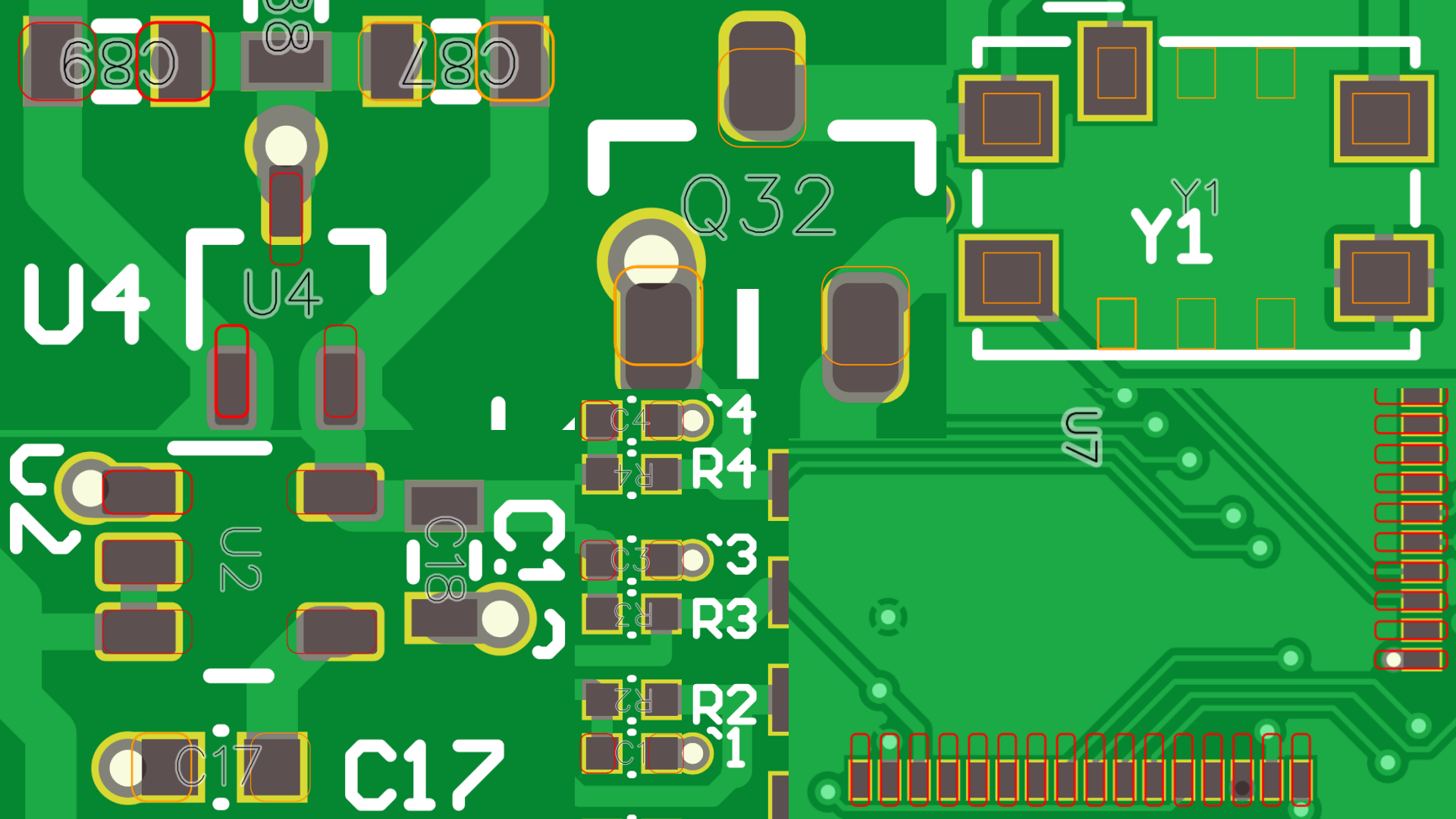


Component specs not respected in the PCB layout



- Footprint – check CAD-info against other database
 - Incorrect component chosen. Same device available with different packages
 - Incorrect footprint definition in CAD library





U4

U4

Q32

Y1

U2

U2

C18

C19

C4

R4

C3

R3

R2

R2

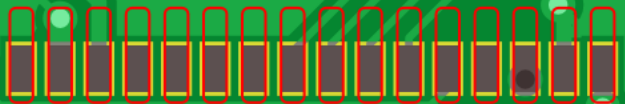
C1

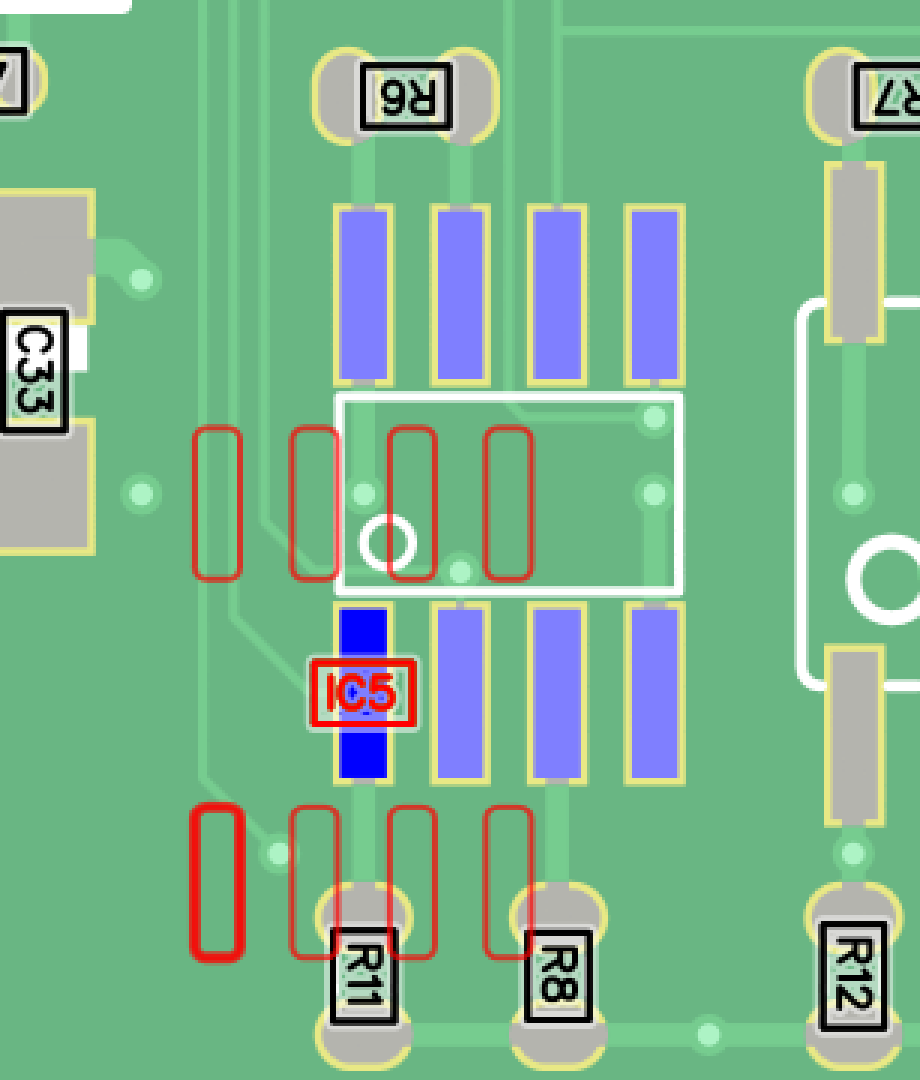
C1

C17

C17

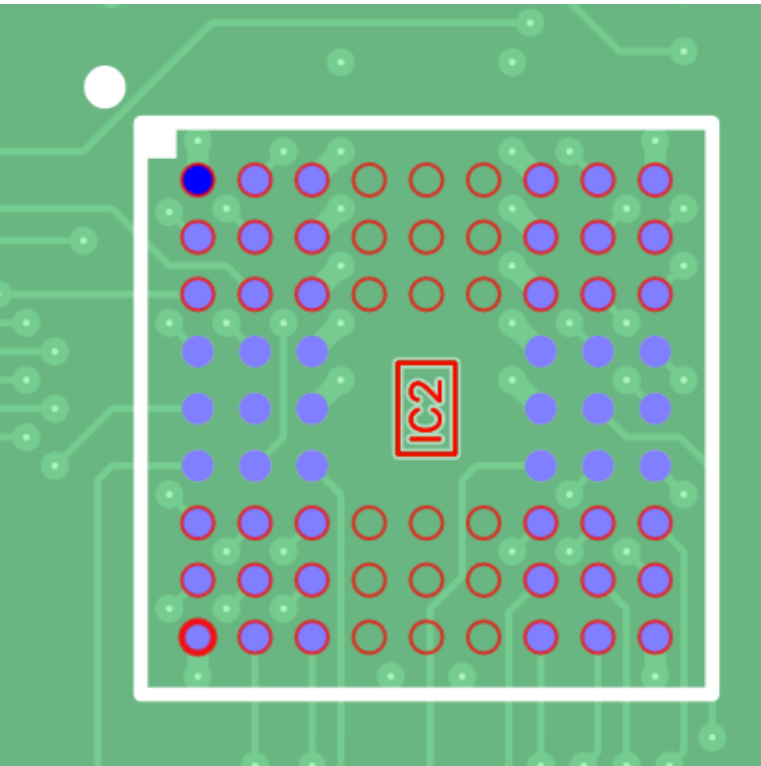
U7



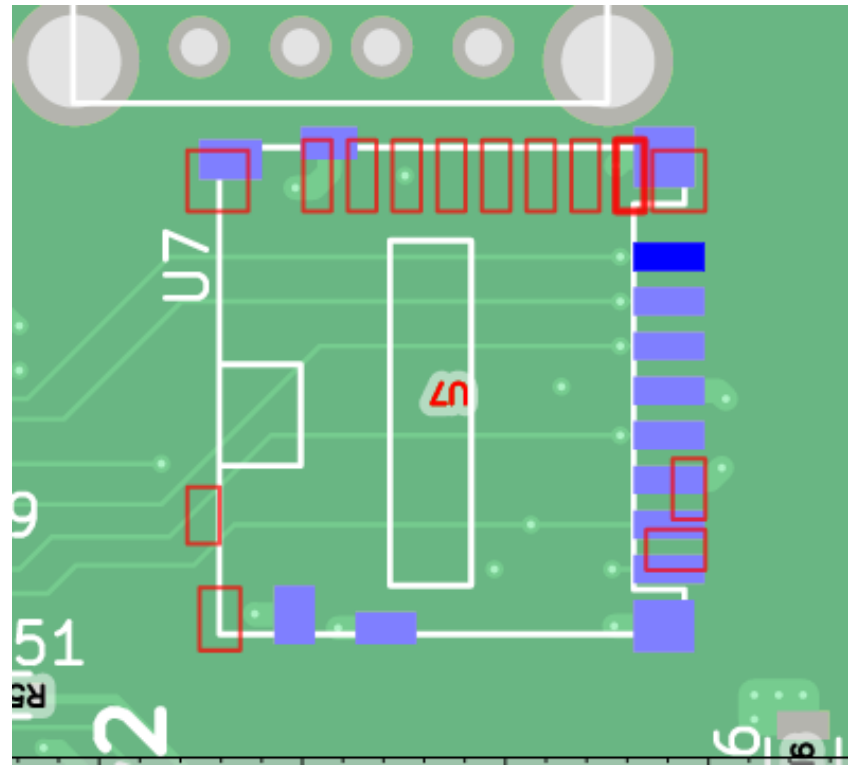


- Location
 - PIN1 vs centroid location in Component Placement List file

- Rotation
 - Each library can define its own default rotation
 - CAD – ERP - Machine



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no clear polarity

L3

L3

No polarity
indication
between
Component
Placement List
and Gerber data



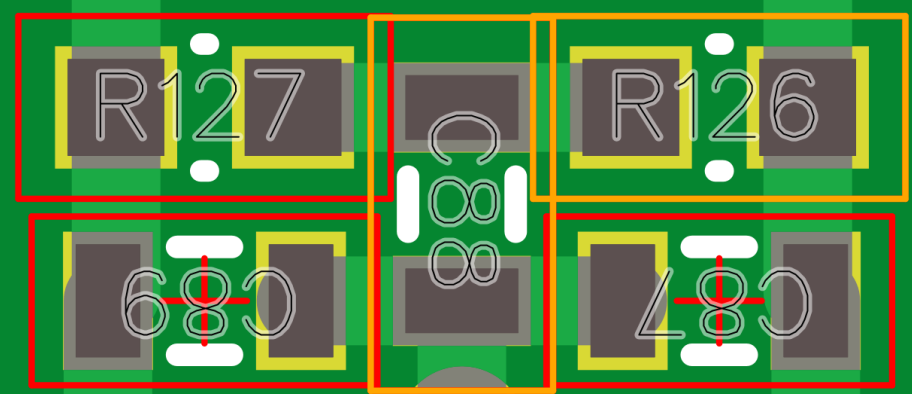


legend and CPL in contradiction

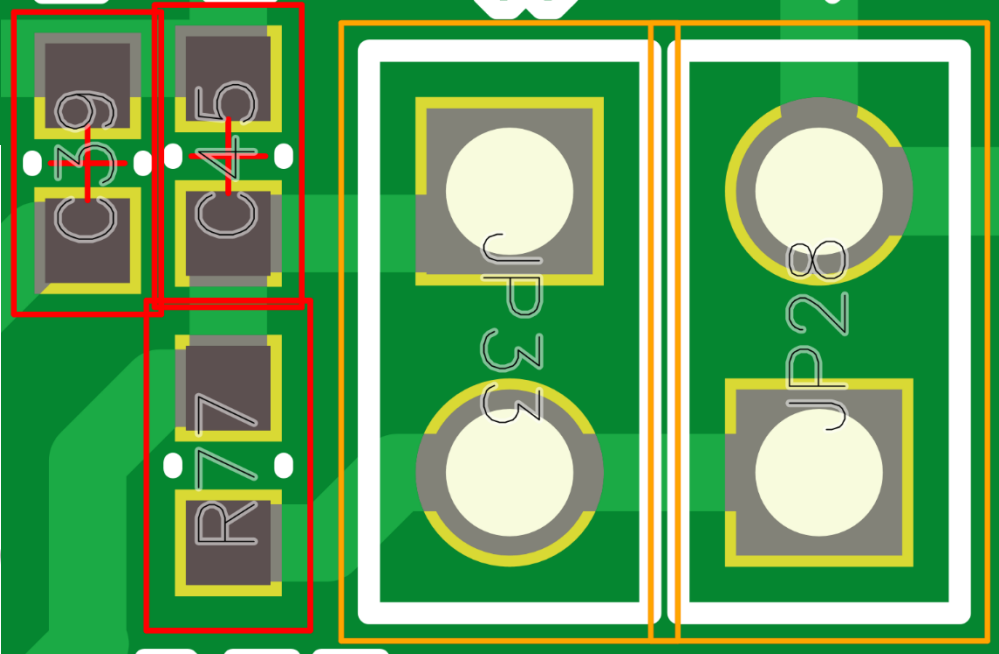
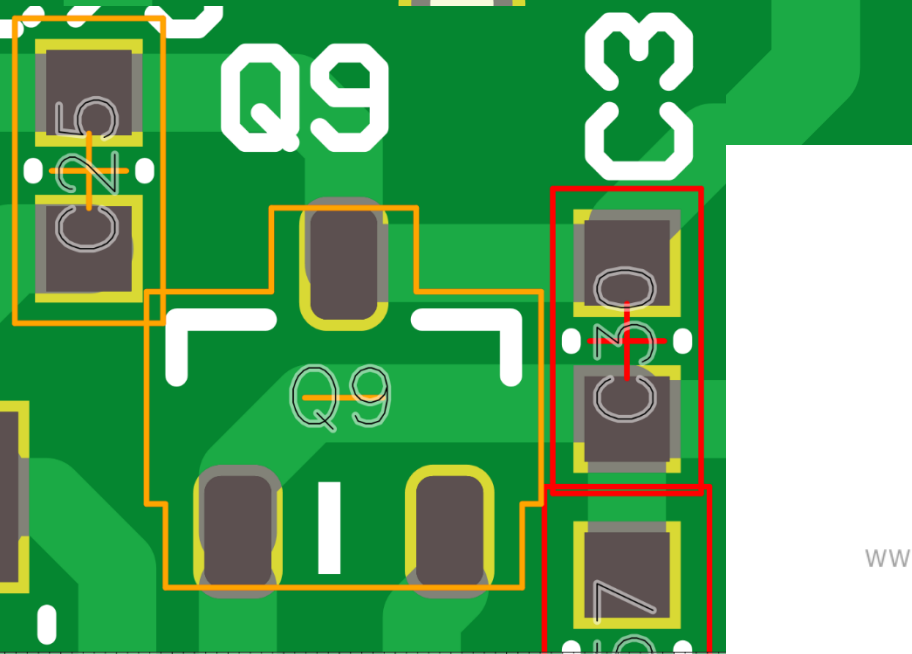
TS.NL

Contradictory
data in
Component
Placement List
and legend
(Gerber data)





IPC component contour/keep out not respected



CAD to CAM

optimum PCB design flow

01

First Think

02

Then Act

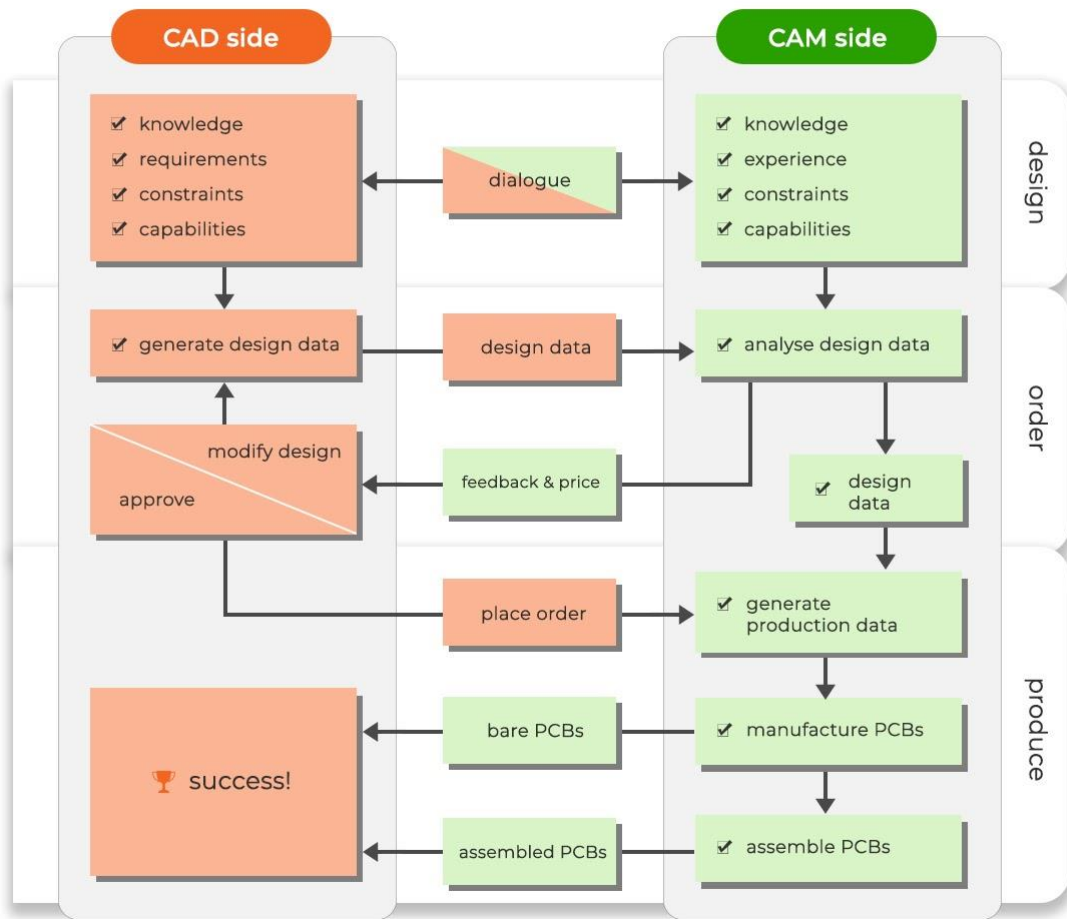
03

Achieve
"Right First Time"

- In time
- On Budget



BRIDGING THE GAP
BETWEEN CAD AND CAM



Virtual production
of your electronics

How?



EURO



CIRCUITS

- Your board “right first time”
 - on time
 - accurate to your intentions
 - at best total cost
- Thanks
- Visit us at booth 9C090





Who are we?

- Prototypes & Small Series, produced & assembled in house
- Almost 100% of our sales = online
- 2022 figures:
 - +/- 500 Eurocircuits colleagues
 - + 12.000 professional customers (20.000 users) in Europe
 - + 110.000 orders
 - +/-40 M€ consolidated sales
- Started 1991, is Belgian and is privately owned
- Factories in Hungary and Germany & Engineering in India
- Local sales in Belgium (HQ), France, Germany, UK, Switzerland, Italy, Spain and Hungary